## DSC2G02

## Silicon NPN epitaxial planar type

For high-frequency amplification

#### ■ Features

- High transition frequency f<sub>T</sub>
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

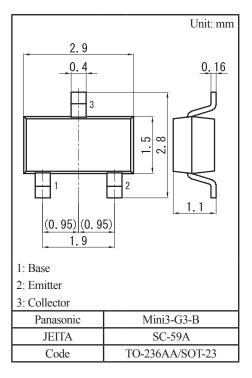
#### ■ Marking Symbol: C5

#### Packaging

DSC2G02×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	3	V	
Collector current	$I_{\rm C}$	15	mA	
Collector power dissipation	P <sub>C</sub>	200	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



### ■ Electrical Characteristics $T_a = 25$ °C±3°C

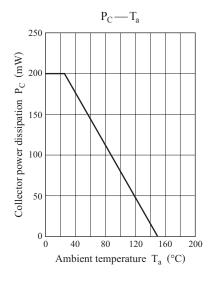
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu A, I_E = 0$	30			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 10 \mu A, I_C = 0$	3			V
Base-emitter voltage	V <sub>BE</sub>	$V_{CE} = 6 \text{ V}, I_C = 1 \text{ mA}$		0.72		V
Forward current transfer ratio *1	h <sub>FE</sub>	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	65		260	_
Transition frequency	$f_T$	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	450	650		MHz
Reverse transfer capacitance (Common emitter)	C <sub>re</sub>	V <sub>CE</sub> = 6 V, I <sub>C</sub> = 1 mA, f = 10.7 MHz		0.6		pF
Power gain	PG	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		24		dB
Noise figure	NF	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		3.3		dB

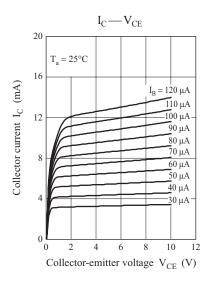
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

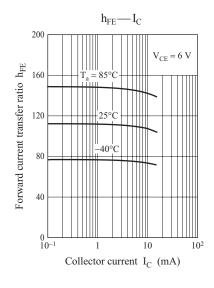
#### 2. \*1: Rank classification

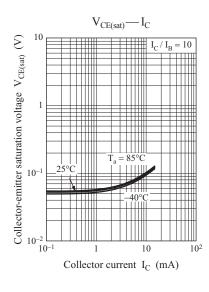
Code	С	D	0	
Rank	С	D	No-rank	
$h_{\mathrm{FE}}$	65 to 160	100 to 260	65 to 260	
Marking Symbol	C5C	C5D	C5	

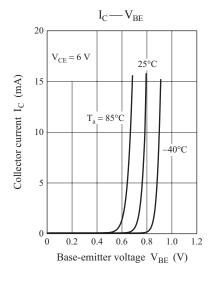
Product of no-rank is not classified and have no marking symbol for rank.

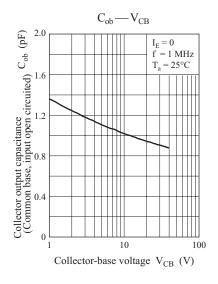


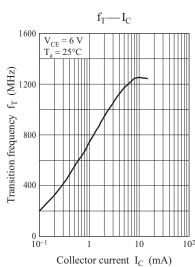








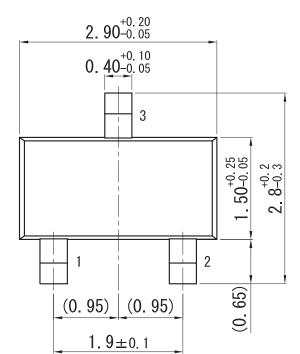


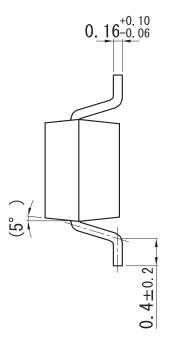


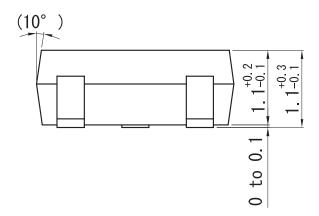
Ver. BED 2

Unit: mm

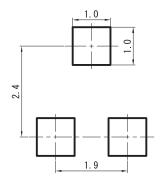
Mini3-G3-B







### ■ Land Pattern (Reference) (Unit: mm)



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